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(11) **EP 0 779 655 A3**

(12) **EUROPEAN PATENT APPLICATION**

(88) Date of publication A3:
16.07.1997 Bulletin 1997/29

(51) Int Cl.6: **H01L 21/768, H01L 21/304**

(43) Date of publication A2:
18.06.1997 Bulletin 1997/25

(21) Application number: **96307792.0**

(22) Date of filing: **29.10.1996**

(84) Designated Contracting States:
DE FR GB

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(30) Priority: **14.12.1995 US 572362**

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(54) **A method of chemically-mechanically polishing an electronic component**

(57) A method of chemically polishing aluminum from a semiconductor wafer to leave a wiring pattern thereon. The surface of the aluminum in aqueous environment consists of hydrated alumina; upon contact with the hydrated silica particles of a polishing slurry at

neutral pH, the surface alumina is transferred to the surface of the silica by aluminosilicate formation removing the alumina layer by layer by contact chemical reaction. Wafers thus polished have nearly scratch-free and corrosion-free polished aluminum lines in an insulator surface.

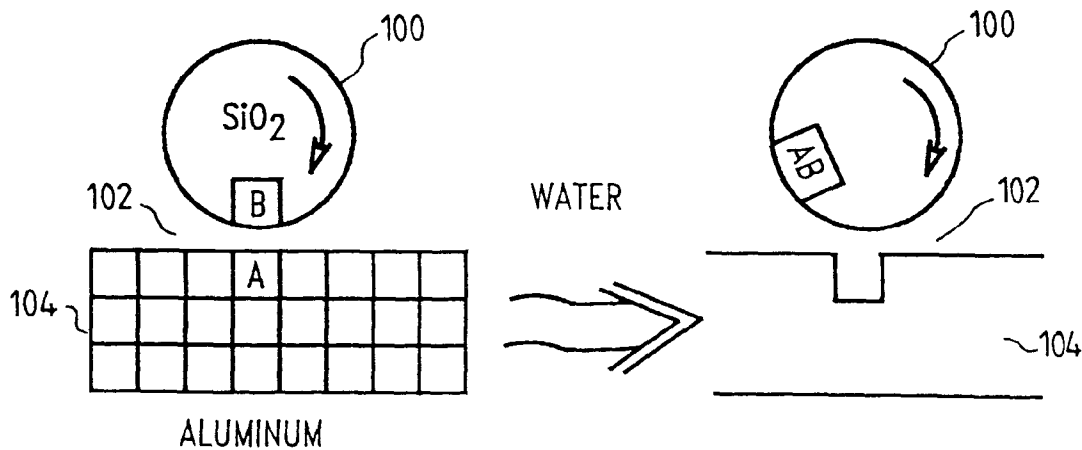


FIG. 2 B

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EUROPEAN SEARCH REPORT

Application Number
EP 96 30 7792

| DOCUMENTS CONSIDERED TO BE RELEVANT | | | |
|--|--|---|--|
| Category | Citation of document with indication, where appropriate, of relevant passages | Relevant to claim | CLASSIFICATION OF THE APPLICATION (Int.Cl.6) |
| Y | US 4 944 836 A (BEYER KLAUS D ET AL) 31 July 1990 * column 2, line 59 - column 3, line 17 * * column 7, line 2 - column 7, line 29 * * claim 5; figure 3 * --- | 1-3,7,10 | H01L21/768 H01L21/304 |
| Y | US 5 328 553 A (POON STEPHEN S) 12 July 1994 * column 4, line 60 - column 5, line 11 * * claim 1; figures 5,6 * --- | 1-3,7,10 | |
| A | US 4 789 648 A (CHOW MELANIE M ET AL) 6 December 1988 * column 3, line 15 - line 57; figures 4-6 * --- | 1-3 | |
| A | US 5 352 277 A (SASAKI SHIGEO) 4 October 1994 * column 16, line 39 - line 68 * --- | 4 | |
| A | EP 0 379 361 A (MINNESOTA MINING & MFG) 25 July 1990 * claim 4 * --- | 8 | TECHNICAL FIELDS SEARCHED (Int.Cl.6) H01L |
| A | EP 0 685 877 A (SHINETSU HANDOTAI KK) 6 December 1995 * column 2, line 50 - column 3, line 18 * ----- | 10 | |
| The present search report has been drawn up for all claims | | | |
| Place of search THE HAGUE | | Date of completion of the search 24 April 1997 | Examiner Hammel, E |
| <p>CATEGORY OF CITED DOCUMENTS</p> <p>X : particularly relevant if taken alone Y : particularly relevant if combined with another document of the same category A : technological background O : non-written disclosure P : intermediate document</p> <p>T : theory or principle underlying the invention E : earlier patent document, but published on, or after the filing date D : document cited in the application L : document cited for other reasons & : member of the same patent family, corresponding document</p> | | | |

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